





# **Table of Contents**

Overview	č
Higher Switching Efficiency	4
SiC Discretes and Modules Nomenclature	
Discrete Products	
Power Modules	
AgileSwitch Gate Driver Solutions	
SiC Reference Designs	
Notes	.11



### Overview

### **Breakthrough Technology Combines High Performance With Low Losses**

Silicon Carbide (SiC) semiconductors provide an innovative option for power electronic designers looking for improved system efficiency, smaller form factor and higher operating temperature in products covering industrial, transportation/automotive, medical, aerospace/aviation, defense and communcation market segments. Our next-generation SiC MOSFETs and SiC SBDs are designed with higher repetitive Unclamped Inductive Switching (UIS) capability at rated on-resistance or current. Our SiC MOSFETs maintain high UIS capability at approximately 10–25 Joules Per Square Centimeter (J/cm²) and robust short circuit protection. Microchip's SiC Schottky Barrier Diodes (SBDs) are designed with balanced surge current, forward voltage, thermal resistance and thermal capacitance ratings at low reverse current for lower switching loss. In addition, our SiC MOSFET and SiC SBD die can be paired together for use in modules. SiC MOSFET and SiC SBD products from Microchip will be qualified to the AEC-Q101 standard.

- Extremely-low switching losses improves system efficiency
- High-power density for smaller footprint to reduce size and weight
- 3× more thermally conductive than silicon

- Reduced sink requirements to achieve smaller size, lighter weight
- High-temperature operation improves reliability at increased power density
- Proven reliability/ruggedness, supply chain and support with Microchip quality, supply and support

SiC is the perfect technology to address high-frequency and high-power density applications Lower power losses Higher frequency cap. Higher junction temp.



Easier cooling
Downsized system
Higher reliability

#### **Automotive**

#### Industrial

**Aviation** 

#### **Defense**

### Medical













QSS

- Quality: proven reliability and ruggedness
- Supply: risk averse approach throughout the supply chain
- **Support:** standard discrete, die, module, and gate drive solutions with design and application support for customers





### **Higher Switching Efficiency**

SiC is the ideal technology for higher-switching-frequency, higher-efficiency and higher-power (>650 V) applications. Target markets and applications include:

- Industrial—Motor drives, welding, UPS, SMPS, induction heating
- Transportation/automotive—Electric Vehicle (EV) battery chargers, on board chargers, Hybrid Electric Vehicle (HEV) powertrains, DC-DC converters, energy recovery
- Smart energy—Photovoltaic (PV) inverters, wind turbines
- Medical—MRI power supply, X-ray power supply
- Commercial aviation—Actuation, air conditioning, power distribution
- Defense—Motor drives, auxiliary power supplies, integrated vehicle systems

SiC MOSFET and SiC Schottky Barrier Diode products increase your system efficiency over silicon MOSFET and IGBT solutions while lowering your total cost of ownership by enabling downsized systems and smaller/lower-cost cooling.

### Advanced R&D and Manufacturing

#### Design

- TCAD design and process simulators
- Mask-making and layout
- Finite Element Analysis (FEA) and Electrothermal simulation capabilities
- Design for ruggedness

#### **Process**

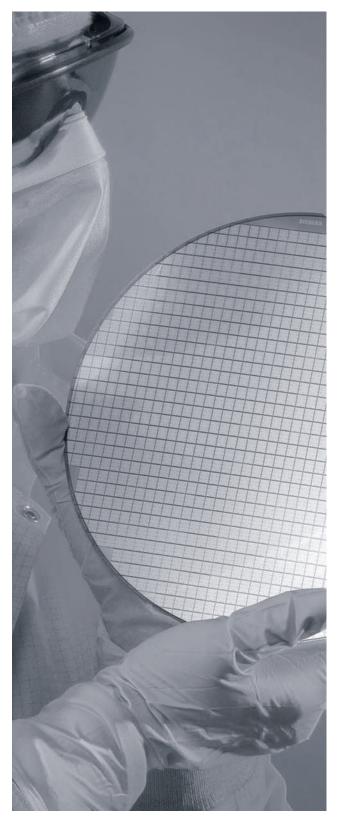
- Automotive quality internal fab and foundry
- Propietary gate oxide process with exceptional reliability
- Specialized tools for SiC processes implant, anneal, etch, furnaces, metal deposition

### **Analytical and Support**

- Full FA capabilities in-house
- SEM/EDAX
- Thermal imaging
- Photo Emission Microscope system (Phemos 1000)

### **Reliability Testing and Screening**

- AEC-Q101
- Full suite of tools and equipment for burn-ins and reliability screening
- Sonoscan and X-ray

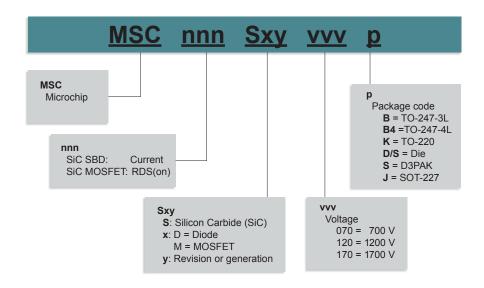




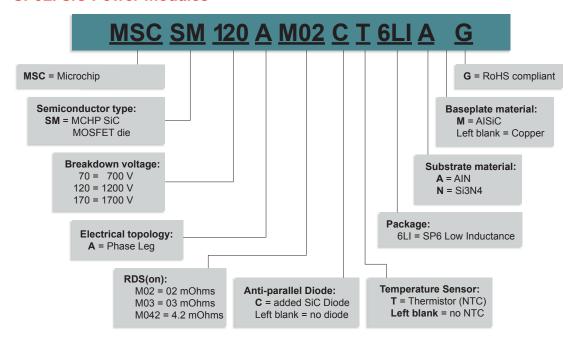


### SiC Discretes and Modules Nomenclature

### **SiC Discretes**



### **SP6LI SiC Power Modules**







### **Discrete Products**

### **SiC Schottky Barrier Diodes**

Part Number	Voltage (V)	I <sub>F</sub> (A)	Package
MSC010SDA070B		10	TO-247
MSC010SDA070K		10	TO-220
MSC030SDA070B	700	30	TO-247
MSC030SDA070K		30	TO-220
MSC050SDA070B		50	TO-247
MSC010SDA120B		10	TO-247
MSC010SDA120K	1200	10	TO-220
MSC015SDA120B		15	TO-247
MSC015SDA120K		15	TO-220
MSC030SDA120B		30	TO-247
MSC030SDA120K		30	TO-220
MSC030SDA120S		30	D3PAK
MSC050SDA120B		50	TO-247
MSC050SDA120S		50	D3PAK
MSC010SDA170B		10	TO-247
MSC030SDA170B	1700	30	TO-247
MSC050SDA170B		50	TO-247

### **SiC MOSFETs**

Part Number	Voltage (V)	RDSon (mΩ)	Package
MSC090SMA070B		00	TO-247
MSC090SMA070S		90	D3PAK
MSC060SMA070B			TO-247
MSC060SMA070B4		60	TO-247-4L
MSC060SMA070S			D3PAK
MSC035SMA070B	700		TO-247
MSC035SMA070B4		35	TO-247-4L
MSC035SMA070S			D3PAK
MSC015SMA070B			TO-247
MSC015SMA070B4		15	TO-247-4L
MSC015SMA070S			D3PAK
MSC080SMA120B			TO-247
MSC080SMA120B4		80	TO-247-4L
MSC080SMA120S		80	D3PAK
MSC080SMA120J			SOT-227
MSC040SMA120B			TO-247
MSC040SMA120B4	1200 40	TO-247-4L	
MSC040SMA120S	1200	40	D3PAK
MSC040SMA120J			SOT-227
MSC025SMA120B			TO-247
MSC025SMA120B4		25	TO-247-4L
MSC025SMA120S		25	D3PAK
MSC025SMA120J			SOT-227
MSC750SMA170B			TO-247
MSC750SMA170B4		750	TO-247-4L
MSC750SMA170S	1700		D3PAK
MSC035SMA170B	1700		TO-247
MSC035SMA170B4		35	TO-247-4L
MSC035SMAS170S			D3PAK

### **SiC MOSFET Features and Benefits**

Characteristics	SiC vs. Si	Results	Benefits
Breakdown field (MV/cm)	10× higher	Lower on-resistance	Higher efficiency
Electron sat. velocity (cm/s)	2× higher	Faster switching	Size reduction
Bandgap energy (ev)	3× higher	Higher junction temperature	Improved cooling
Thermal conductivity (W/m.K)	3× higher	Higher power density	Higher current capabilities
Positive temperature coefficient		Self regulation	Easy paralleling





TO-247-3L









TO-220

TO-268

SOT-227



### **Power Modules**

### **Power Module Advantages**

- High-speed switching
- Low switching losses
- Low-input capacitance
- High-power density
- Low-profile packages
- Minimum parasitic inductance
- Lower system cost
- Standard and custom modules
- 30+ years design experience

Part Number	Туре	Electrical Topology	Voltage (V)	RDSon (mΩ)	Current (A) Tc = 80 C	Package	Notes
MSC2X30/31SDA070J				-	30	SOT-227	
MSC2X50/51SDA070J			700	-	50	SOT-227	
MSC2X100/101SDA070J		Dual diode		-	100	SOT-227	
MSC2X30/31SDA120J		(Anti-parallel/parallel)		-	30	SOT-227	
MSC2X50/51SDA120J			1200	-	50	SOT-227	
MSC2X100/101SDA120J				-	100	SOT-227	
MSCDC50H701AG			700	-	50	SP1	
MSC50DC70HJ					50	SOT-227	
MSCDC100H70AG			700	-	100	SP6	
MSCDC200H70AG				-	200	SP6	
MSCDC50H1201AG				-	50	SP1	
MSC50DC120HJ		E #1. : 1	1000	-	50	SOT-227	
MSCDC100H120AG		Full bridge	1200	-	100	SP6	
MSCDC200H120AG				-	200	SP6	
MSCDC100H170AG				-	100	SP6C	
MSCDC200H170AG			4700	-	200	SP6C	
MSCDC50H1701AG			1700	-	50	SP1	
MSC50DC170HJ				-	50	SOT-227	
MSCDC100A70D1PAG				-	100	D1P	
MSCDC150A70D1PAG				-	150	D1P	
MSCDC200A70D1PAG	SiC Diode			-	200	D1P	
MSCDC300A70AG	Module		700	-	300	SP6	
MSCDC450A70AG				-	450	SP6	
MSCDC600A70AG				-	600	SP6	
MSCDC100A120D1PAG				-	100	D1P	
MSCDC150A120D1PAG				-	150	D1P	
MSCDC200A120D1PAG		DI I		-	200	D1P	
MSCDC300A120AG		Phase leg	1200	-	300	SP6	
MSCDC450A120AG				-	450	SP6	
MSCDC600A120AG				-	600	SP6	
MSCDC300A170AG				-	300	SP6C	
MSCDC450A170AG				-	450	SP6C	
MSCDC600A170AG				-	600	SP6C	
MSCDC100A170D1PAG			1700	-	100	D1P	
MSCDC150A170D1PAG				-	150	D1P	
MSCDC200A170D1PAG				-	200	D1P	
MSCDC100KK70D1PAG			700	-	100	D1P	
MSCDC150KK70D1PAG				-	150	D1P	
MSCDC200KK70D1PAG		Dual common		-	200	D1P	
MSCDC100KK120D1PAG		cathode		-	100	D1P	
MSCDC150KK120D1PAG			1200	-	150	D1P	
MSCDC200KK120D1PAG				-	200	D1P	







## **Power Modules**

Part Number Type Electrical Topology	Voltage (V)	RDSon (mΩ)	Current (A) Tc = 80 C	Package	Notes
MSCDC100KK170D1PAG		-	100	D1P	
MSCDC150KK170D1PAG  Dual commo	n 1700	-	150	D1P	
MSCDC200KK170D1PAG SiC Diode		-	200	D1P	
MSCDC50X701AG Module	4000	-	50	SP1	
MSCDC50X1201AG Three phase br	1200 idge	-	50	SP1	
MSCDC50X1701AG	1700	-	50	SP1	
MSC100SM70JCU2		15	97	SOT-227	
MSC100SM70JCU3	700	15	97	SOT-227	
MSC40SM120JCU2		40	44	SOT-227	
MSC70SM120JCU2 Boost chopp	er	25	71	SOT-227	
MSC130SM120JCU2		12.5	138	SOT-227	
MSCSM120DAM11CT3AG		11	202	SP3F	
MSC40SM120JCU3	1200	40	44	SOT-227	
MSC70SM120JCU3		25	71	SOT-227	
MSC130SM120JCU3	er	12.5	138	SOT-227	
MSCSM120SKM11CT3AG		11	202	SP3F	
MSCSM70HM19CT3AG	700	15	97	SP3F	
MSCSM120HM31CT3AG	700	25	71	SP3F	
Full bridge	1000				
MSCSM120HM16CT3AG	1200	12.5	138	SP3F	
MSCSM120HM50CT3AG		40	44	SP3F	
MSCSM70AM19CT1AG		15	97	SP1F	
MSCSM70AM07CT3AG		5	276	SP3F	
MSCSM70AM10CT3AG	700	7.5	188	SP3F	
MSCSM70AM025CD3AG SiC MOSFET		2.5	538	D3	
MSCSM70AM025CT6AG Module		2.5	538	SP6C	
MSCSM120AM16CT1AG		12.5	138	SP1F	
MSCSM120AM31CT1AG Phase leg		25	71	SP1F	
MSCSM120AM50CT1AG		40	44	SP1F	
MSCSM120AM08CT3AG		6.25	268	SP3F	
MSCSM120AM11CT3AG	1200	8.33	202	SP3F	
MSCSM120AM042CD3AG		4.2	394	D3	2, 3
MSCSM120AM027CD3AG		2.7	584	D3	2, 3
MSCSM120AM042CT6AG		4.2	394	SP6C	
MSCSM120AM027CT6AG		2.7	584	SP6C	
MSCSM70VM19C3AG	log	15	97	SP3F	
MSCSM70VM10C4AG Vienna phase	ley	7.5	97	SP4	
MSCSM70TAM19CT3AG	700	15	97	SP3F	
MSCSM70TAM10CTPAG		7.5	186	SP6P	
MSCSM70TAM05TPAG Three hase brid	dge	5	273	SP6P	
MSCSM120TAM31CT3AG Triple phase le		25	71	SP3F	
MSCSM120TAM16CTPAG	1200	12.5	136	SP6P	
MSCSM120TAM11CTPAG		8.33	200	SP6P	
MSCSM70AM025CT6LIAG			538	SP6C LI	
	700	2.5			
MSCSM120AM042CT6LIAG	700	4.2	394	SP6C LI	1
MSCSM120AM042CT6LIAG Low Inductance MSCSM120AM03CT6LIAG SiC MOSFET Module Phase leg	700				1

<sup>1, 2, 3</sup> Refer to Gate Driver Solutions table on page 9



# **AgileSwitch Gate Driver Solutions**

Gate Driver Reference*	Gate Driver Type		Adapter Board Part Number	
1	Core	2ASC-12A1HP	SP6CA1	
2	Core	2ASC-12A1HP	62CA1	
3	Plug & Play	62EM1-00001	Not Applicable	

<sup>\*</sup>Refer to footnotes in SiC product tables

### 2ASC-12A1HP



Improve switching efficiency and EMI performance, all while protecting your valuable SiC devices. The AgileSwitch 2ASC dual-channel high performance gate driver cores are designed to take on your SiC implementation challenges.

# 62CA1 and SP6CA1 (Shown with 2ASC-12A1HP connected)





Compatible with the AgileSwitch 2ASC Gate Driver Cores, the family of Module Adapter Boards provides a platform to rapidly evaluate and optimize new SiC power devices. Standard offerings include a reference design for the 1200V SP6LI (SP6CA1) and 1200V D3 (62CA1).

### 62EM1



Control, monitor, and protect the latest 62 mm SiC devices using the Plug-and-Play 62EM Gate Driver Boards. Designed for traction applications, the 62EM can drive up to 1.7 kV devices at 100 kHz with configurable fault settings and patented Augmented Switching technology.





### SiC Reference Designs

### **User-Friendly Reference Designs**

Microchip and our partner ecosystem provide open-source, user friendly SiC MOSFET reference design solutions that enable faster time to market for customers using our SiC MOSFETs and power modules. You can use isolated dual-gate driver reference designs with our SiC MOSFETS in a number of SiC topologies.

### **SiC Reference Designs**

Part Number	Gate Drive or Line Voltage	KHz, max	Per Side Drive Power (W)	Description
MSCSICMDD/REF	-5 to +20 V	400	8 W	SiC discrete gate driver board
MSCSICSP3/REF2	-5 to +20 V	400	16 W	SiC SP3 module driver board
MSCSICSP6L/REF3	-5 to +20 V	400	16 W	SiC SP6LI module driver board
MSCSICPFC/REF5	In: 400 Vrms, Out: 700 Vdc	140	30 kW	30 kW 3-phase Vienna PFC (design files only)



The MSCSICMDD/REF1 is a switch-configurable high/low-side driver with half bridges or independent drive.

- 400 kHz maximum switching frequency
- 8W of gate drive power per side
- 30A peak output current
- –5V/+20 V gate drive voltage
- ±100 kV/uS capability
- Galvanic isolation of more than 2000V on both gate drivers



The MSCSICPFC/REF5 is a Vienna 3-Phase PFC reference design for Hybrid Electric Vehicle/Electric Vehicle (HEV/EV) charger and high-power switch mode power supply applications.

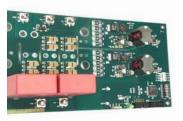
- 30 kW Vienna rectifier topoloy at 98.6 % peak efficiency
- 380/400 VAC, 50 Hz/60 Hz input voltage with 700V DC output voltage
- 140 kHz pulse-width modulation switching frequency
- < 5% current THD at half and full loads</li>
- 700 V SiC MOSFETs and 1200 V SiC diodes
- dsPIC33CH using 3-level modulation for digital control





The MSCSICSP3/REF2 is a half bridge driver compatible with SP3F standard package modules.

- 400 kHz maximum switching frequency
- 16W of gate drive power per side
- 30A peak output current
- –5 V/+20 V gate drive voltage
- ±100 kV/uS capability
- Galvanic isolation of more than 2000 V on both gate drivers





The MSCSICSP6/REF3 is a half bridge driver for the low inductance SP6LI power modules.

- Stray inductance < 3 nH to fully benefit from SiC
- Designed to be easy to parallel
- Up to 1200 V and 586 A
- Half Bridge Driver
- Up to 400 kHz switching frequency
- 12 V VIN supply
- Capable of 16 W of gate drive power/side
- 30 A Peak Source output current
- Min.100 KV/µS CMTI

